# PATENT ASSIGNMENT

Electronic Version v1.1  
Stylesheet Version v1.1

<table>
<thead>
<tr>
<th>SUBMISSION TYPE:</th>
<th>NEW ASSIGNMENT</th>
</tr>
</thead>
<tbody>
<tr>
<td>NATURE OF CONVEYANCE:</td>
<td>ASSIGNMENT</td>
</tr>
</tbody>
</table>

## CONVEYING PARTY DATA

<table>
<thead>
<tr>
<th>Name</th>
<th>Execution Date</th>
</tr>
</thead>
<tbody>
<tr>
<td>Kei Obata</td>
<td>09/23/2010</td>
</tr>
<tr>
<td>Junichi Inoue</td>
<td>09/23/2010</td>
</tr>
<tr>
<td>Akito Kuriyama</td>
<td>09/23/2010</td>
</tr>
<tr>
<td>Akihiro Shibata</td>
<td>09/27/2010</td>
</tr>
<tr>
<td>Kentaroh Ishikawa</td>
<td>09/23/2010</td>
</tr>
</tbody>
</table>

## RECEIVING PARTY DATA

<table>
<thead>
<tr>
<th>Name:</th>
<th>Sony Corporation</th>
</tr>
</thead>
<tbody>
<tr>
<td>Street Address:</td>
<td>1-7-1 Konan, Minato-ku</td>
</tr>
<tr>
<td>City:</td>
<td>Tokyo</td>
</tr>
<tr>
<td>State/Country:</td>
<td>JAPAN</td>
</tr>
</tbody>
</table>

PROPERTY NUMBERS Total: 1

<table>
<thead>
<tr>
<th>Property Type</th>
<th>Number</th>
</tr>
</thead>
<tbody>
<tr>
<td>Application Number:</td>
<td>12895993</td>
</tr>
</tbody>
</table>

## CORRESPONDENCE DATA

Fax Number: (312)827-8185  
*Correspondence will be sent via US Mail when the fax attempt is unsuccessful.*

Phone: 3128074310  
Email: chicago.patents@klgates.com  
Correspondent Name: Thomas C. Basso  
Address Line 1: P.O. Box 1135  
Address Line 2: K&L Gates LLP  
Address Line 4: Chicago, ILLINOIS 60690-1135

**ATTORNEY DOCKET NUMBER:** 3712174-02373

**NAME OF SUBMITTER:** Thomas C. Basso

Total Attachments: 2

---

**PATENT**  
**REEL: 025118 FRAME: 0672**

**501316170**
ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventors (if plural names are listed below) of certain new and useful improvements in

ALIGNMENT FILM AND METHOD OF MANUFACTURING THE SAME, PHASE DIFFERENCE DEVICE AND METHOD OF MANUFACTURING THE SAME, AND DISPLAY UNIT

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Kamio, Minato-ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar ($1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designees, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and in proofs in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my said said invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 12/895,993, Filing Date: October 1, 2010

This assignment executed on the dates indicated below.

KEI OBATA
Name of first or sole inventor
MIYAGI JAPAN
Residence of first or sole inventor (Kei Obata)
Signature of first or sole inventor

JUNICHI INOUE
Name of second inventor
TOCHIGI JAPAN
Residence of second inventor (Junichi Inoue)
Signature of second inventor

AKITO KURIYAMA
Name of third inventor
TOCHIGI JAPAN
Residence of third inventor (Akito Kuriyama)
Signature of third inventor

Execution date of U.S. Patent Application

September 23, 2010
Date of this assignment

Execution date of U.S. Patent Application

September 23, 2010
Date of this assignment

Execution date of U.S. Patent Application

September 23, 2010
Date of this assignment